

# Preliminary Investigation of Heat Transfer and Thermal Distribution in Computer Mainboard based on Finite Element Analysis

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A Higher operating temperature increases a risk of mainboard in computer malfunction. In this work, the heat transfer and thermal distribution on a mainboard were investigated based on finite element analysis. We proposed boundary conditions and parameters at least to be defined. The results of simulation were compared with the actual results measured by the thermal imager. The comparison shows reasonably good agreement between both results. One of the impacts from this study is a methodology applying to set a practice for student learning.

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